

AMENDMENTS TO THE ABSTRACT

Please substitute the following paragraph(s) for the abstract now appearing in the currently filed specification.

A3
A temperature control system for ~~multiple process components in~~ a semiconductor processing facility includes a common cooling unit for controlling the temperature of a cooling fluid and multiple remote temperature control modules ~~in fluid communications with the common cooling unit~~ that separately control the temperatures of the multiple process components. The ~~remote~~ temperature control modules are ~~located~~ near the process components and each ~~remote temperature control module~~ includes a circulation loop for the cooling fluid from the common cooling unit and a circulation loop for a heat transfer fluid ~~that is received~~ from a ~~process~~ component. A heat exchanger within the ~~remote~~ temperature control module allows heat ~~to be transferred from~~ between the heat transfer fluid ~~to~~ and the cooling fluid, thereby ~~providing~~ cooling to the ~~process~~ component. A heat source may also be ~~included~~ within the ~~remote~~ temperature control module to ~~provide~~ heat to the heat transfer fluid and ~~therefore to~~ the ~~process~~ component. The cooling unit may be a refrigeration unit that provides compressed refrigerant to the ~~remote~~ temperature control modules which ~~and the remote temperature control modules~~ may include an upstream thermal expansion valve and a downstream refrigerant flow control valve that form an evaporation chamber ~~for the compressed refrigerant~~.